

Advanced Packaging (Part 2)

Friday, 30 September 2011 16:10 (1 hour)

- Requirements to and technologies for IC packaging.
- Overview of different packaging technologies and their specific applications.
- Packaging for high reliability applications.
- Pitfalls and challenges in IC Packaging.
- Advanced 3D packaging (chip on chip / die on die / etc.).

Presenter: Mr VAL

Session Classification: TUTORIAL - Advanced Packaging (Part 2)